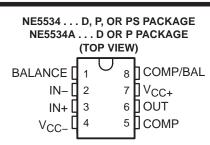
SLOS070B - JULY 1979 - REVISED FEBRUARY 2004

- Equivalent Input Noise Voltage . . .
 3.5 nV/√Hz
- Unity-Gain Bandwidth . . . 10 MHz Typ
- Common-Mode Rejection Ratio . . .
 100 dB Typ
- High DC Voltage Gain . . . 100 V/mV Typ
- Peak-to-Peak Output Voltage Swing
 32 V Typ With V_{CC±} = ±18 V and R_L = 600 Ω
- High Slew Rate . . . 13 V/μs Typ
- Wide Supply-Voltage Range ±3 V to ±20 V
- Low Harmonic Distortion
- Offset Nulling Capability
- External Compensation Capability



description/ordering information

The NE5534 and NE5534A are high-performance operational amplifiers combining excellent dc and ac characteristics. Some of the features include very low noise, high output-drive capability, high unity-gain and maximum-output-swing bandwidths, low distortion, and high slew rate.

These operational amplifiers are compensated internally for a gain equal to or greater than three. Optimization of the frequency response for various applications can be obtained by use of an external compensation capacitor between COMP and COMP/BAL. The devices feature input-protection diodes, output short-circuit protection, and offset-voltage nulling capability with use of the BALANCE and COMP/BAL pins (see the application circuit diagram).

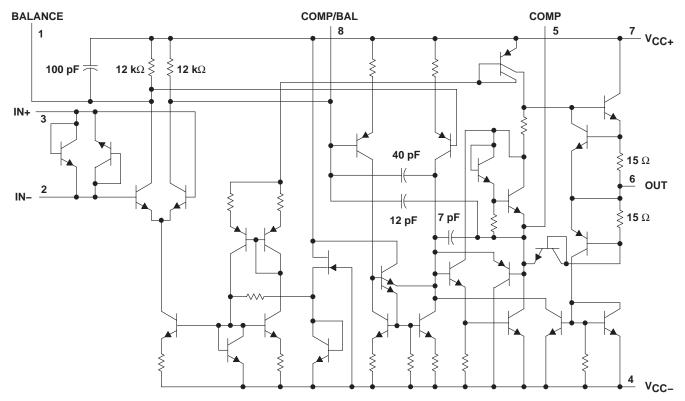
For the NE5534A, a maximum limit is specified for the equivalent input noise voltage.

ORDERING INFORMATION

TA	V _{IO} max AT 25°C	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
0°C to 70°C	4 mV	PDIP (P)	Tube of 50	NE5534P	NE5534P	
			Tube of 50	NE5534AP	NE5534AP	
		SOIC (D)	Tube of 75	NE5534D	NESSOA	
			Reel of 2500	NE5534DR	NE5534	
			Tube of 75	NE5534AD	55044	
			Reel of 2500	NE5534ADR	5534A	
		SOP (PS)	Reel of 2000	NE5534PS	N5534	

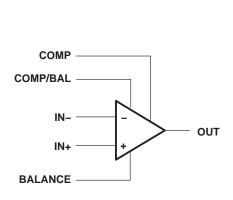
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

schematic

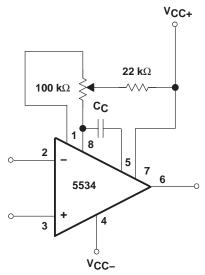


All component values shown are nominal.

symbol



application circuit



Frequency Compensation and Offset-Voltage Nulling Circuit



NE5534, NE5534A LOW-NOISE OPERATIONAL AMPLIFIERS

SLOS070B - JULY 1979 - REVISED FEBRUARY 2004

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage: V _{CC+} (see Note 1)		22 V
V _{CC} – (see Note 1)		
Input voltage either input (see Notes 1 and 2)		V _{CC+}
Input current (see Note 3)		±10 mA
Duration of output short circuit (see Note 4)		Unlimited
Package thermal impedance, θ _{JA} (see Notes 5 and 6):	: D package	97°C/W
	P package	85°C/W
	PS package	95°C/W
Operating virtual junction temperature, T _J		150°C
Storage temperature range, T _{stq}		−65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
 - 2. The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
 - 3. Excessive current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
 - 4. The output may be shorted to ground or to either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
 - 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 6. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
V _{CC+}	Supply voltage	5	15	V
VCC-	Supply voltage	-5	-15	V



SLOS070B – JULY 1979 – REVISED FEBRUARY 2004

electrical characteristics, $V_{CC}\pm$ = ±15 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP	MAX	UNIT
.,		$V_{O} = 0$,	T _A = 25°C		0.5	4	.,
VIO	Input offset voltage	$R_S = 50 \Omega$	T _A = Full range			5	mV
	Input offset current	V _O = 0	T _A = 25°C		20	300	^
lio			T _A = Full range			400	nA
I	Langet biles assume at		T _A = 25°C		500	1500	~ ^
I _{IB}	Input bias current	V _O = 0	T _A = Full range			2000	nA
VICR	Common-mode input voltage range			±12	±13		V
\/ - · ·		D. > 000 O	$V_{CC\pm} = \pm 15 \text{ V}$	24	26		V
VO(PP)	Maximum peak-to-peak output voltage swing	$R_L \ge 600 \Omega$	$V_{CC\pm} = \pm 18 \text{ V}$	30	32		
Δ	Large-signal differential voltage amplification	$V_0 = \pm 10 \text{ V},$	T _A = 25°C	25	100		V/mV
AVD		$R_L \ge 600 \Omega$	T _A = Full range	15			
Λ .	Small-signal differential voltage amplification	f = 10 kHz	CC = 0		6		V/mV
A _{vd}			$C_C = 22 pF$		2.2		
	Maximum-output-swing bandwidth	V _O = ±10 V	CC = 0		200		kHz
Вом			$C_C = 22 pF$		95		
DOM		$V_{CC\pm} = \pm 18 \text{ V},$ $R_L \ge 600 \Omega,$	$V_{O} = \pm 14 \text{ V},$ $C_{C} = 22 \text{ pF}$		70		
B ₁	Unity-gain bandwidth	$C_C = 22 \text{ pF},$	C _L = 100 pF		10		MHz
rį	Input resistance			30	100		kΩ
z ₀	Output impedance	A _{VD} = 30 dB, C _C = 22 pF,	$R_L \ge 600 \Omega$, f = 10 kHz		0.3		Ω
CMRR	Common-mode rejection ratio	V _O = 0, R _S = 50 Ω	VIC = VICRmin,	70	100	_	dB
ksvr	Supply-voltage rejection ratio (ΔV _{CC} /ΔV _{IO)}	$V_{CC+} = \pm 9 \text{ V to } \pm 15 \text{ V},$ $V_{O} = 0$	$R_S = 50 \Omega$,	80	100		dB
los	Output short-circuit current				38		mA
ICC	Supply current	V _O = 0, No load	T _A = 25°C		4	8	mA

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range is $T_A = 0^{\circ}C$ to $70^{\circ}C$.

operating characteristics, $V_{\mbox{CC}}\,\pm$ = ± 15 V, $T_{\mbox{A}}$ = $25^{\circ}\mbox{C}$

PARAMETER		TEGT CONDITIONS	NE5534	NE5534A			
		TEST CONDITIONS	TYP	MIN TYP	MAX	UNIT	
C D	Slew rate	C _C = 0	13	13		\ ,,,	
SR		C _C = 22 pF	6	6		V/μs	
	Rise time	$V_{I} = 50 \text{ mV}, \qquad A_{VD} = 1, \\ R_{L} = 600 \Omega, \qquad C_{C} = 22 \text{ pF}$	20	20		ns	
t _r	Overshoot factor	C _L = 100 pF	20	20		%	
	Rise time	$I_{I} = 50 \text{ mV}, \qquad A_{VD} = 1,$ $I_{L} = 600 \Omega, \qquad C_{C} = 47 \text{ pF}$	50	50		ns	
	Overshoot factor	C _L = 500 pF	35	35		%	
.,	Equivalent input noise voltage	f = 30 Hz	7	5.5	7	nV/√Hz	
Vn		f = 1 kHz	4	3.5	4.5		
	Equivalent input noise current	f = 30 Hz	2.5	1.5		- A (/ I I =	
In		f = 1 kHz	0.6	0.4		pA/√Hz	
F	Average noise figure	$R_S = 5 \text{ k}\Omega$, $f = 10 \text{ Hz to } 20 \text{ kHz}$		0.9		dB	



TYPICAL CHARACTERISTICS[†]

NORMALIZED INPUT BIAS CURRENT AND INPUT OFFSET CURRENT vs

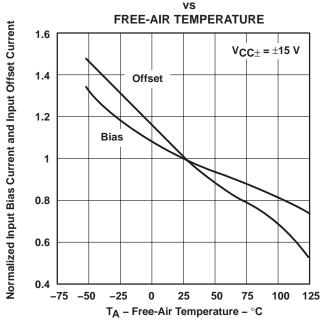
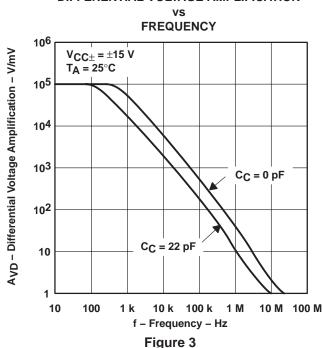


Figure 1

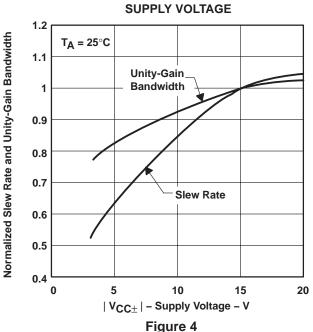
MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE vs **FREQUENCY** Vo(PP) - Maximum Peak-to-Peak Output Voltage - V 30 CC = 025 20 15 10 C_C = 22 pF $C_C = 47 pF$ $V_{CC} \pm = \pm 15 \text{ V}$ T_A = 25°C 100 1 k 10 k 100 k f - Frequency - Hz

Figure 2

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION



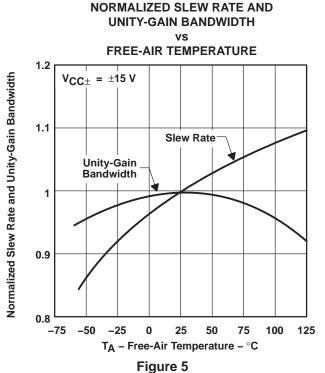
NORMALIZED SLEW RATE AND UNITY-GAIN BANDWIDTH vs

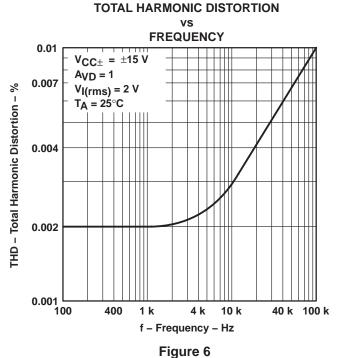


† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

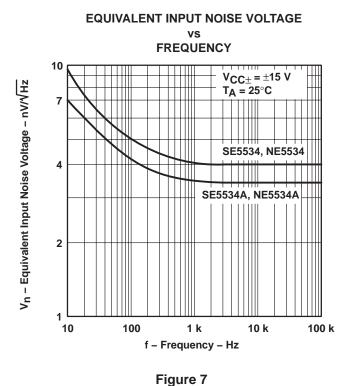


TYPICAL CHARACTERISTICS[†]





•



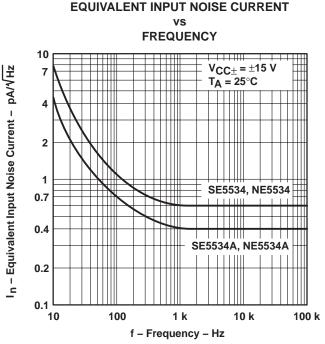


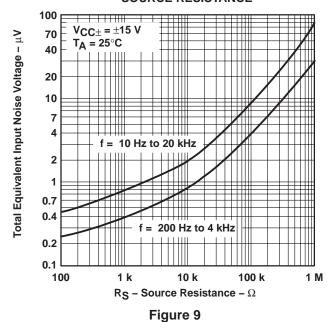
Figure 8

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.



TYPICAL CHARACTERISTICS

TOTAL EQUIVALENT INPUT NOISE VOLTAGE vs SOURCE RESISTANCE



JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



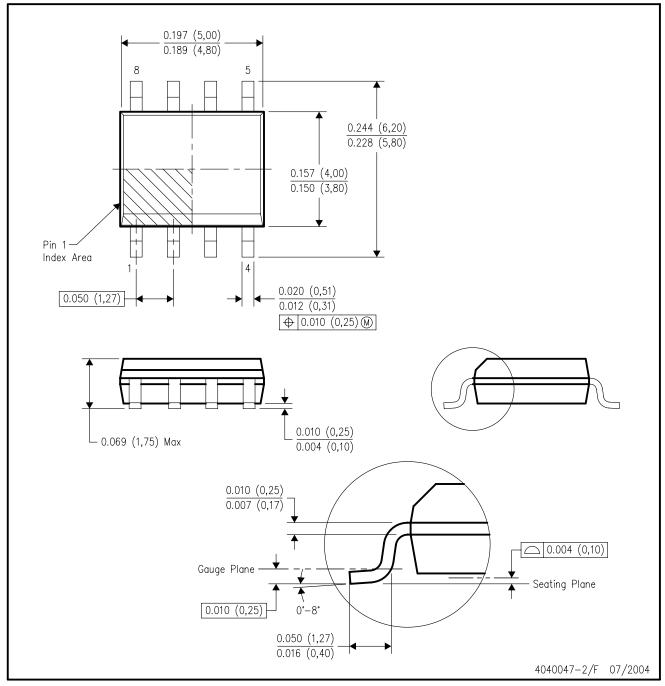
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2004, Texas Instruments Incorporated